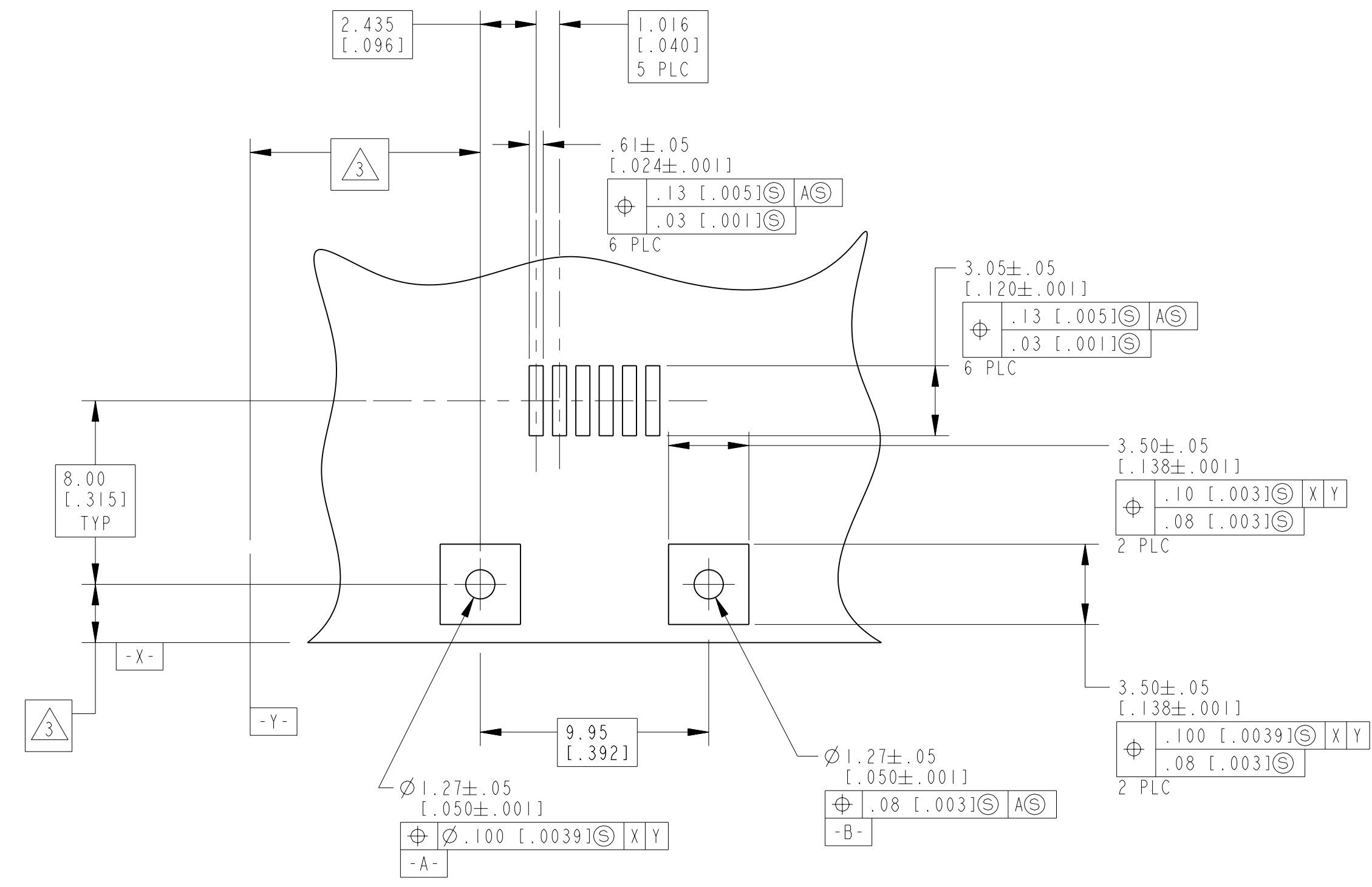
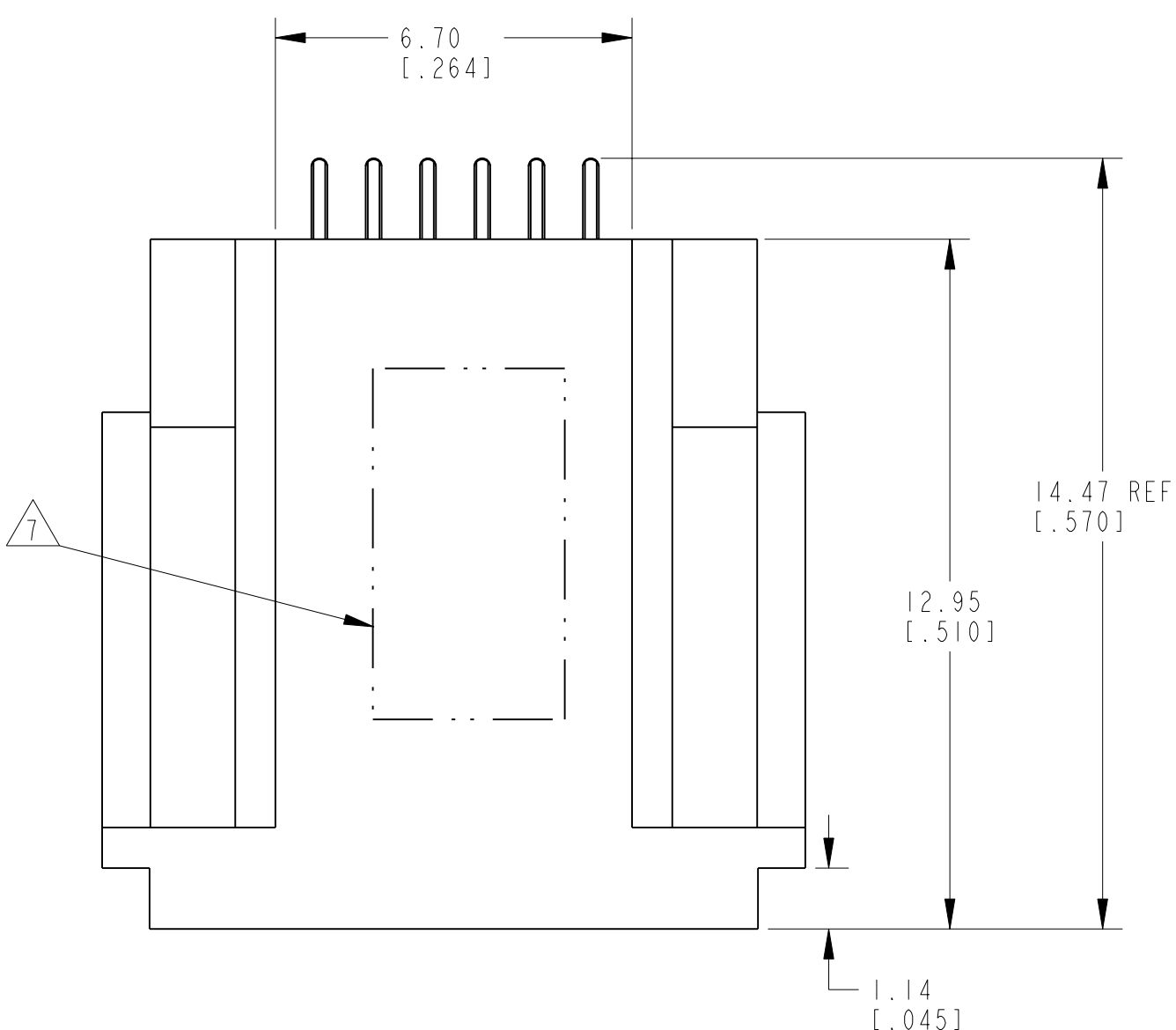
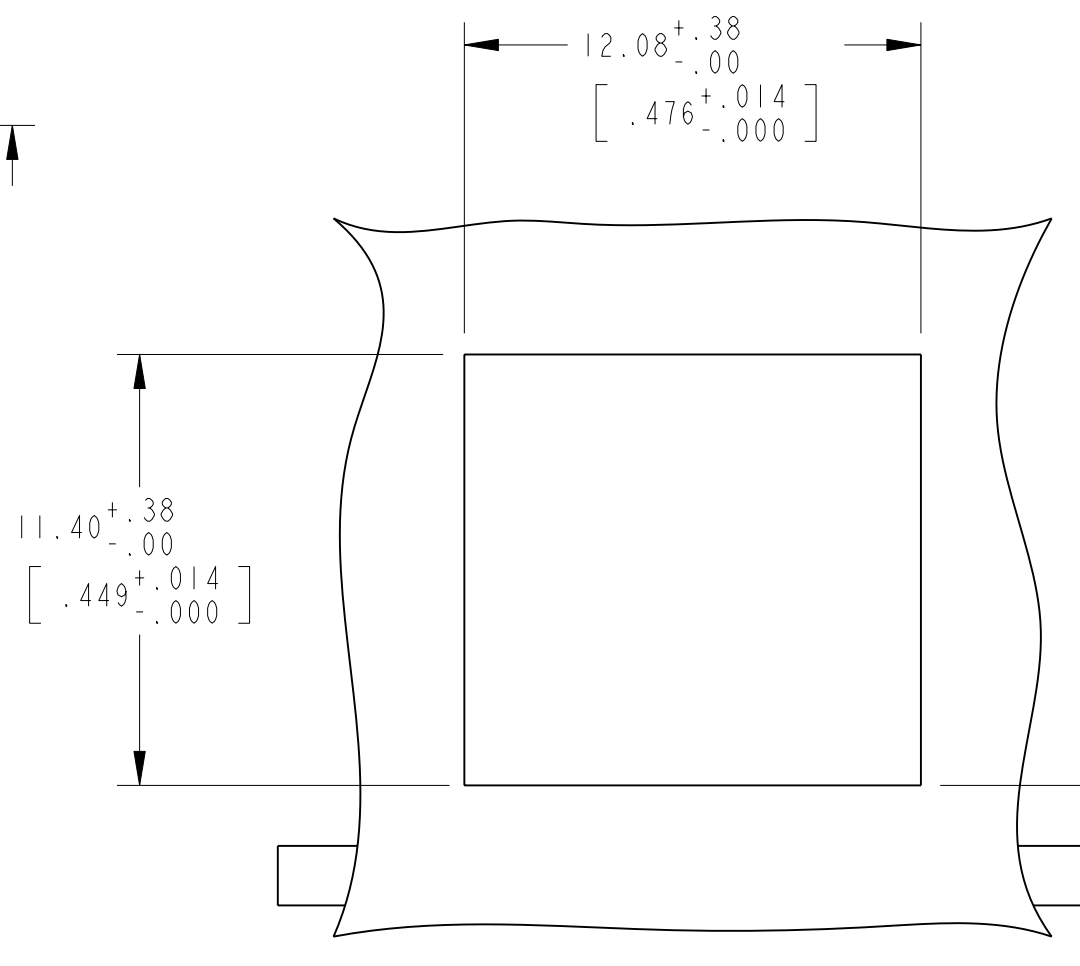
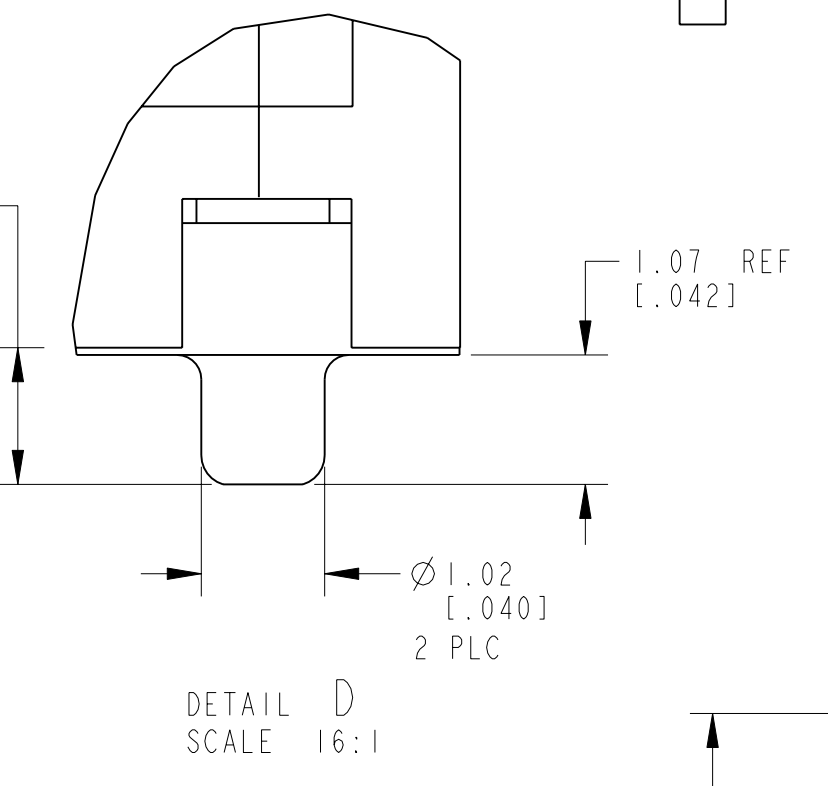
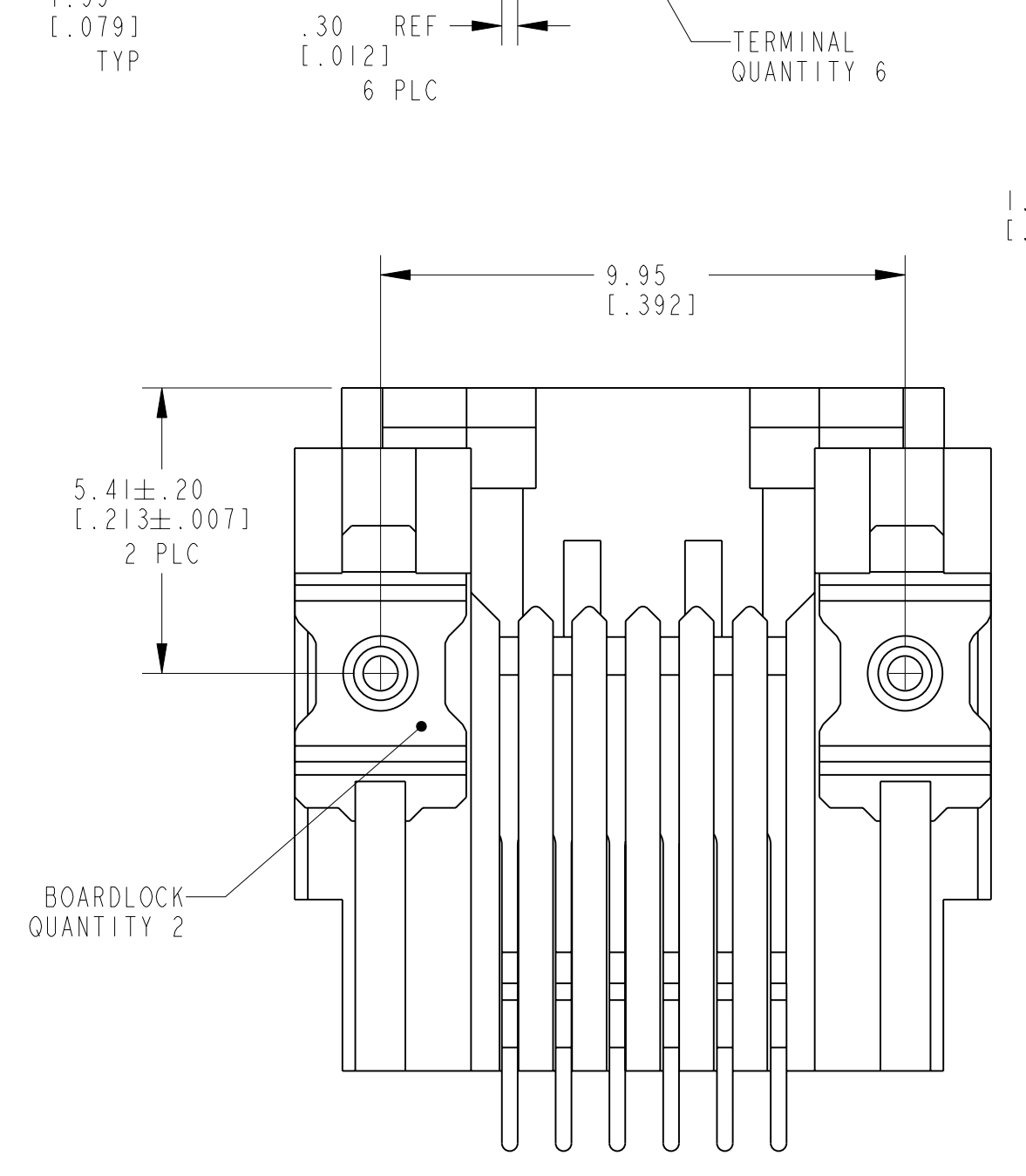
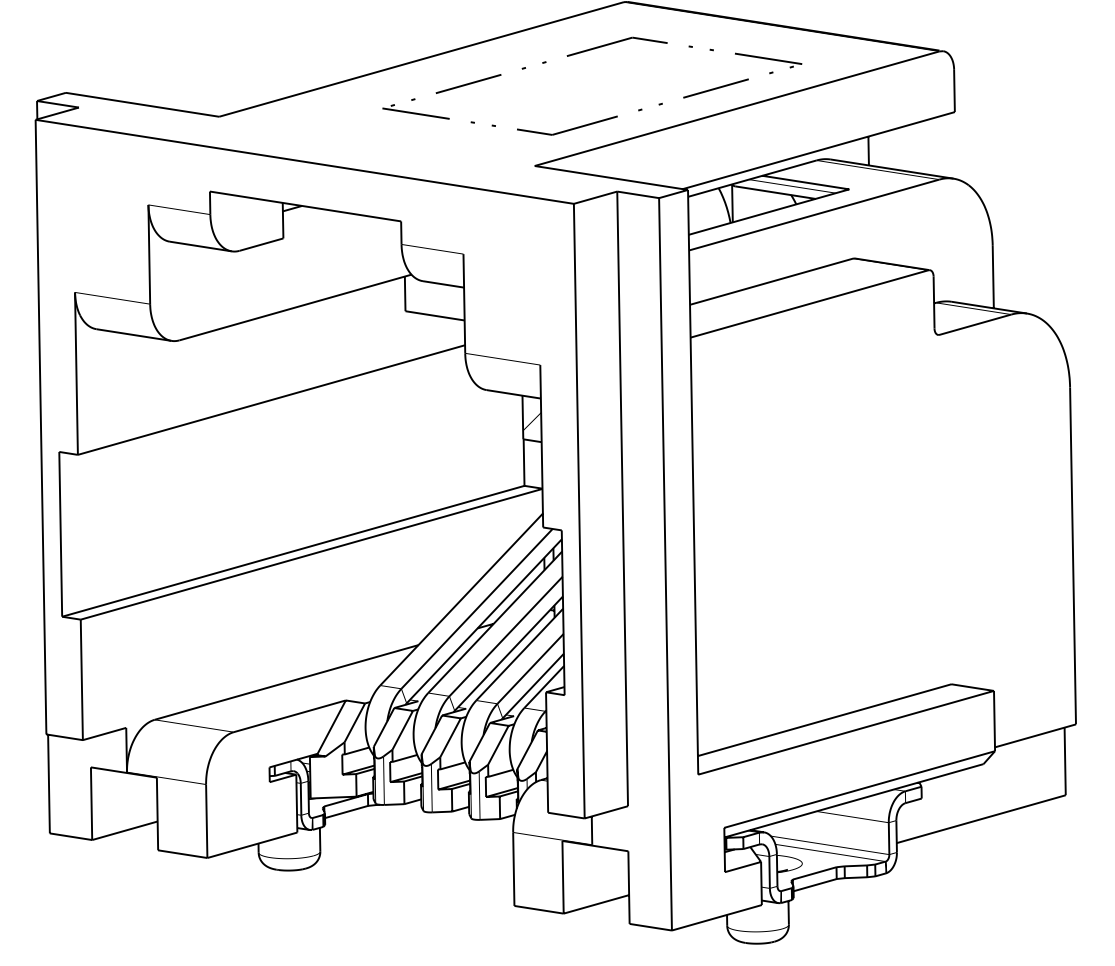
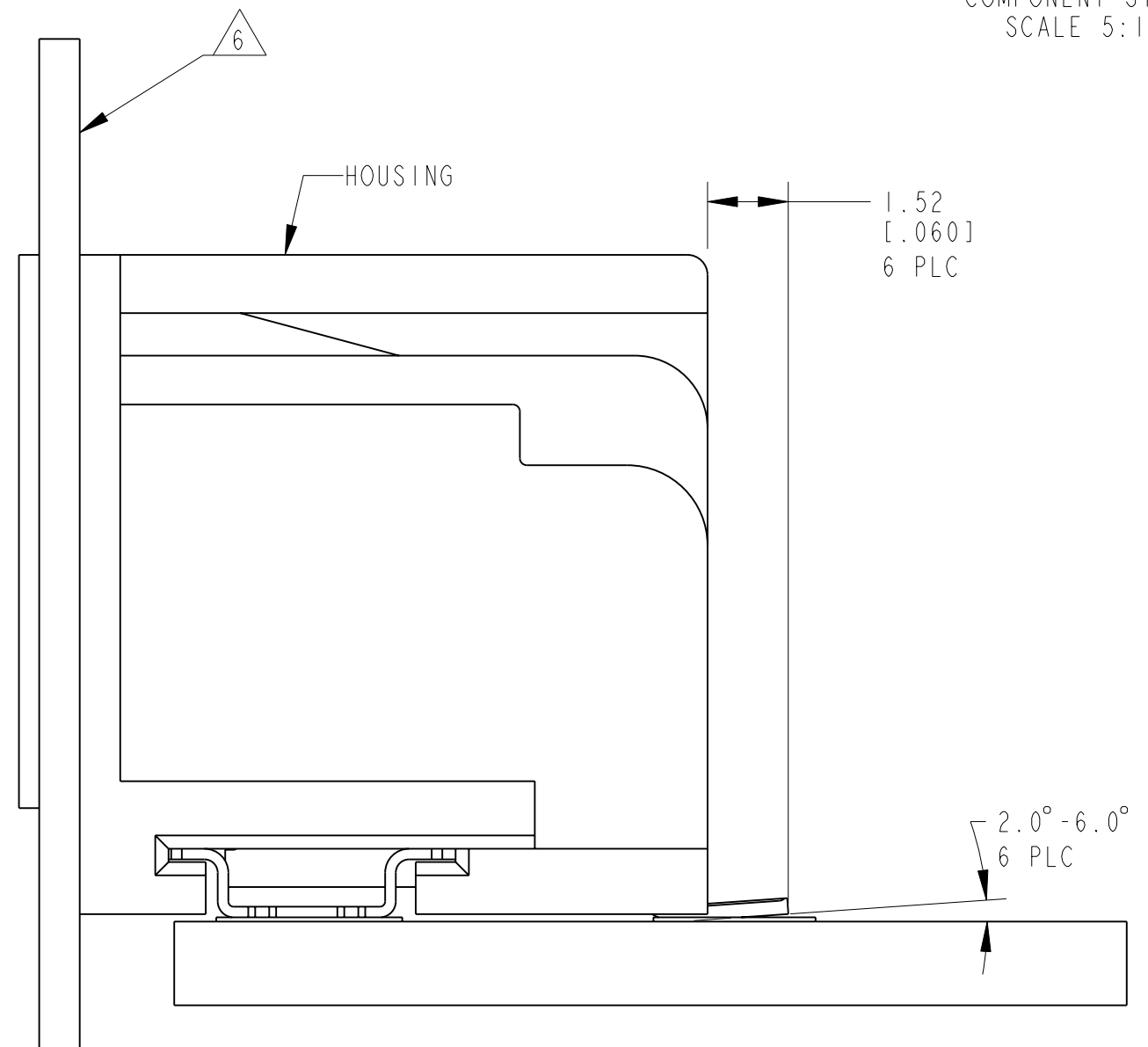
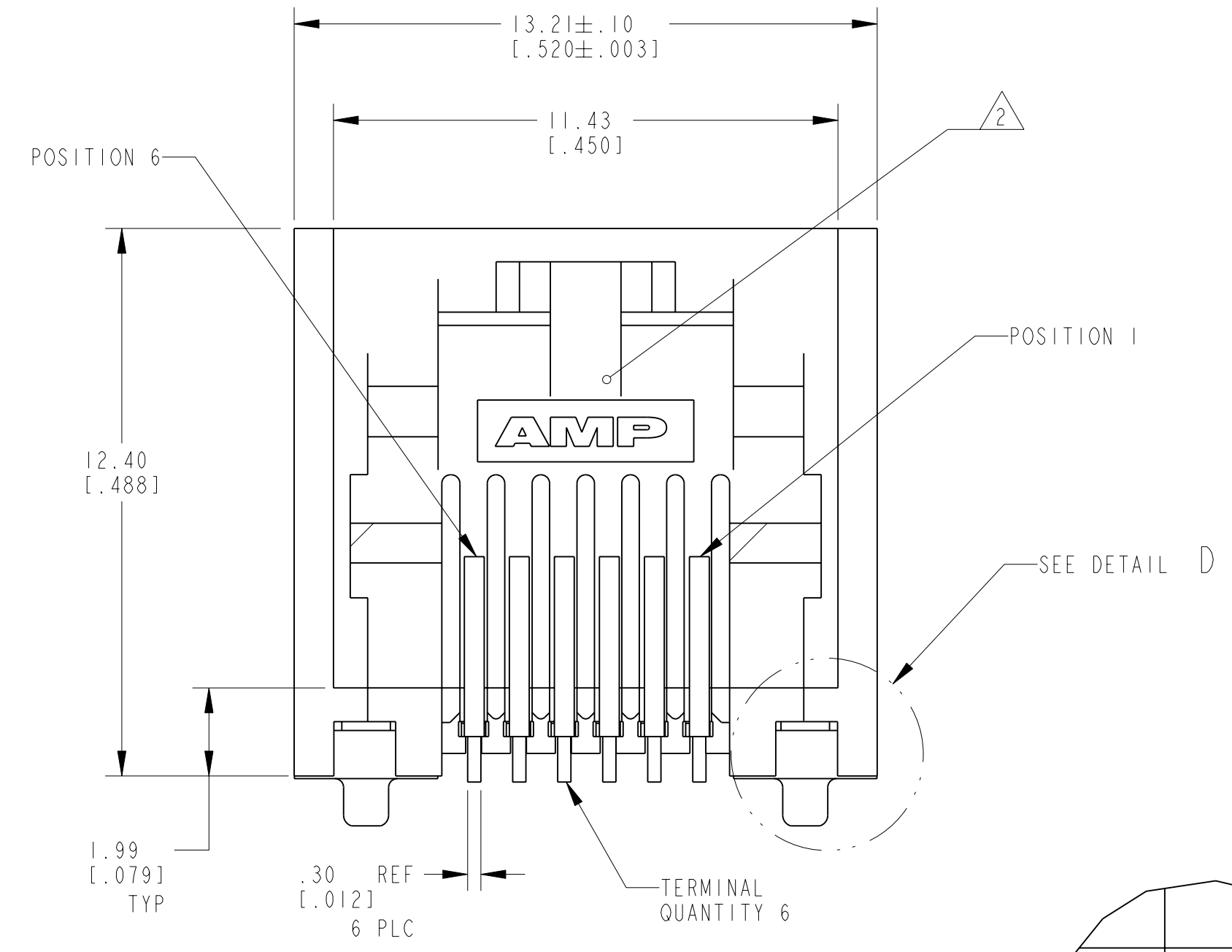


LOC	DIST	REV	DATE	BY	CHK	APPV
AA	22	B1	21MAY2011	RK	HMR	

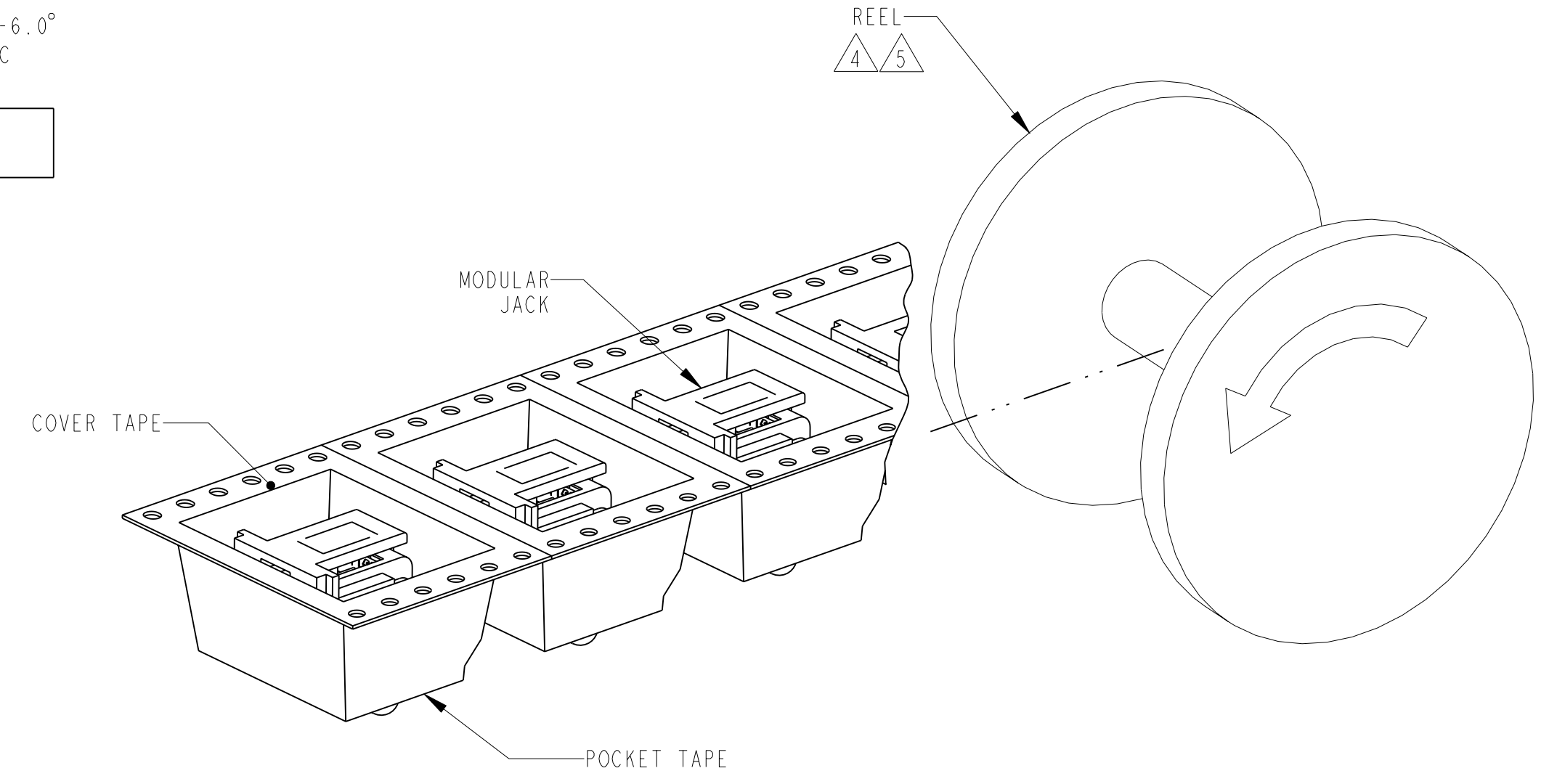
- REVISIONS
- △ MATERIAL: HOUSING - HIGH TEMPERATURE THERMOPLASTIC, COLOR - GRAY  
 TERMINALS - 0.31(.012) THICK COPPER ALLOY PLATED WITH 1.27µm(.000050) MINIMUM GOLD IN LOCALIZED GOLD PLATE AREA, 2.5 µm(.000100) MINIMUM MATTE TIN ON TERMINATION END, BOTH OVER 1.27µm(.000050) MINIMUM NICKEL OVER ENTIRE TERMINAL.  
 BOARDLOCK - PHOS BRONZE, 1/2 HARD, 3.81µm(.000150) MINIMUM MATTE TIN OVER 1.27µm(.000050) MINIMUM NICKEL ON TERMINAL END.
- △ JACK CAVITY CONFORMS TO FCC 47 RULES AND REGULATIONS, PART 68 SUBPART F.
- △ DATUM ESTABLISHED BY CUSTOMER.
- △ PACKAGING TAPE AND REEL: (PER EIA 481 SPEC)  
 32mm WIDE TAPE  
 24mm POCKET PITCH  
 560mm REEL DIA  
 600 PIECES PER REEL
- △ PACKAGING TAPE AND REEL: (PER EIA 481 SPEC)  
 32mm WIDE TAPE  
 24mm POCKET PITCH  
 330mm REEL DIA  
 200 PIECES PER REEL
- △ CONNECTOR SHOULD BE POSITIONED THROUGH PANEL CUTOUT AS SHOWN TO SUPPORT TOP OF MODULAR JACK FOR STRAIN RELIEF
- △ MANUFACTURING DATE CODE LOCATED APPROXIMATELY AS SHOWN. FIRST 2 DIGITS ARE YEAR, SECOND 2 DIGITS ARE WORK WEEK, AND LAST DIGIT IS THE DAY OF THE WEEK



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT  
 COMPONENT SIDE  
 SCALE 5:1



RECOMMENDED PANEL CUTOUT  
 SCALE 5:1



MARKING	PACKAGING	PART NUMBER
NONE	△ 5	5406514-3
△ 7	△ 5	5406514-2
△ 7	△ 4	5406514-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

STE TE Connectivity

MODULAR JACK ASSEMBLY, 6/6 POSITION, SURFACE MOUNT, RIGHT ANGLE, WITH INWARD BOARDLOCKS

WEIGHT: .95 GRAMS

SCALE: 8:1

# Mouser Electronics

Authorized Distributor

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[TE Connectivity:](#)

[5406514-1](#)